

# VLSI-Assignment (2013-Main)

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## Part-A

1) Give two examples for system tasks and compiler directives.

### System task

An identifier beginning with a \$ character is interpreted as a system task (or) system function.

Ex: \$display, \$monitor, \$stop, \$finish are some of the system tasks.

Eg: 1) (\$display task)

// Display the string in quotes  
\$display ("Hello world");

2) (monitor statement)

// monitor time and value of the signal clock and reset  
// clock toggles every 5 time units and reset goes down at 10 times units  
initial begin

\$monitor (\$time, "value of signals clock = %b reset = %b, clock, reset);  
end.

### Compiler directives

All compiler directives are defined by using the <keyword> constant  
certain identifier that start with the (backquote) characters are  
compiler directives.

'define, 'undef, 'ifdef, 'ifndef

Ex: 1) 'define Man\_Bus\_Size 32

'define Result\_Size (Awidth \* Bwidth)

...

sig[Man\_Bus\_Size-1:0] add\_sig.

Ex: 2) 'cell define

module F01\_S0A7(D,clk,0)

input D,clk;

output 0

endmodule

end celldefine

## ② Difference between parallel and sequential blocks.

### Sequential blocks

- In this we use begin and end keywords.
- Statements in a sequential block execute in sequence.
- The statements in a sequential block are processed in the order they are specified.
- A statement is executed only after execution of its preceding statement.

→ of system

```
begin  
  [block {declaration}]  
  procedural statements  
end
```

### Parallel blocks

- The keywords fork and join are used.
- Statements are executed concurrently.
- Statements in parallel blocks are executed concurrently.
- Ordering of statements are controlled by the delay (or) event control assigned to each statement.

of system:

```
fork  
  [block {declaration}]  
  procedural statements  
join.
```

## ③ Difference between task and function and how can we include task.

### Task

→ A task can enable other task and function.

→ Task may execute in non-zero simulation time.

Task may contain delay, event or timing control statement.

Task may have zero or more arguments of type input, output, inout.

Tasks do not return with a value, but can pass multiple values through output and inout arguments.

### Function

A function can enable another function but not task.

Function always execute in simulation time.

Functions must not contain any delay, event or timing control statement.

Function must have at least one input argument. They can have more than one input.

Function always return a single value. They cannot have output and inout arguments.

Write a verilog code for an inverter in multi-level of modelling

```
module not(a,b,out);  
input a,b;  
output out;  
wire c;  
supply1 power;  
supply0 gnd;  
Pmos(c,pwr,b);  
Nmos(out,c,a);  
Nmos(out,gnd,a);  
Nmos(out,gnd,b);  
end module
```

6) What are the modelling tips for logic synthesis.

Use meaningful names for signals and variables

Avoid naming: positive & negative edge triggered flipflop

Use basic building blocks vs use of continuous statements

Use parenthesis to optimize logic strg structure

Use arithmetic operators \*, / and %.

Be careful with multiple assignment to the same variable

Define if-else and case statements explicitly.

6) List the uses of PLI?

PLI can be used to define additional system tasks and function

Application software like translators and delay calculators can be executed with PLI.

PLI can be used to extract design information such as hierarchy, connectivity, fanout and number of logic elements of a certain type.

PLI can be used to write special purpose or customized output display routines

Verilog utility based application software can be written with PLI routine.

7. Explain the types of LOPs?

LOP stands for user define primitives.

There are several types of LOPs

i) combinational

ii) sequential.

combinational LOPs are defined where the output is solely determined by a logical combination of the inputs. A good example is a 4:1 mux.

sequential LOPs take the value of the previous inputs and the current ops to determine the value of the next ops. The value of the output is also the internal state of the LOP. Good examples of sequential LOPs are latches and flipflops.

8. Explain the parallel connection and full connection with example.

Parallel connection: A parallel connection is specified by the symbol ' $\Rightarrow$ ' and is used as shown below

$\langle \text{source\_field} \rangle \Rightarrow \langle \text{destination\_field} \rangle = \langle \text{delay\_value} \rangle$

In parallel connection, each bit in source field connects to its corresponding bit in the destination field.

eg. 4-bit-to-4-bit connection receives delay from each bit in source to each bit in 4-bit-to-4-bit connection both a and out are single bit

$a \Rightarrow out = 9;$

4 vector connection, both a and out are 4-bit vectors  $a[3:0], out[3:0]$

If a is source field, out is destination field.

$a \Rightarrow out = 9;$

If the above statement is shot and rotation

11 four four bit-to-bit connection statements

$a[0] \Rightarrow out[0] = 9;$

$a[1] \Rightarrow out[1] = 9;$

$a[2] \Rightarrow out[2] = 9;$

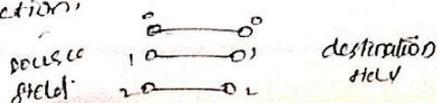
$a[3] \Rightarrow out[3] = 9;$

Illegal connection  $a[4:0]$  is a 5-bit vector,  $out[2:0]$  is 4-bit.

11 mismatch between bit width of source and destination fields

$a \Rightarrow out = 9;$  4-bit width does not match.

Figure of parallel connection:



### All connections

In a full connection, each bit in the source field connects to every bit in the destiny field  
If source and destination are unknown then they need not have the same number of bits

Eg.

// full connection

```
module m1out(a, b, c, d);
```

```
output out;
```

```
input a, b, c, d;
```

```
case 0, 1;
```

// full connection

specify

```
(a, b ==> out) = 9;
```

```
(c, d ==> out) = 11;
```

```
end specify
```

```
and a1 (c, a, b);
```

```
and a2 (b, c, d);
```

```
and a3 (out, e, f);
```

```
end module
```

Q) write verilog code for 2:1 mux using conditional operator.

```
module 2:1 mux(a, b, s, y);
```

```
input a, b, s;
```

```
output y;
```

```
assign y: s ? b : a;
```

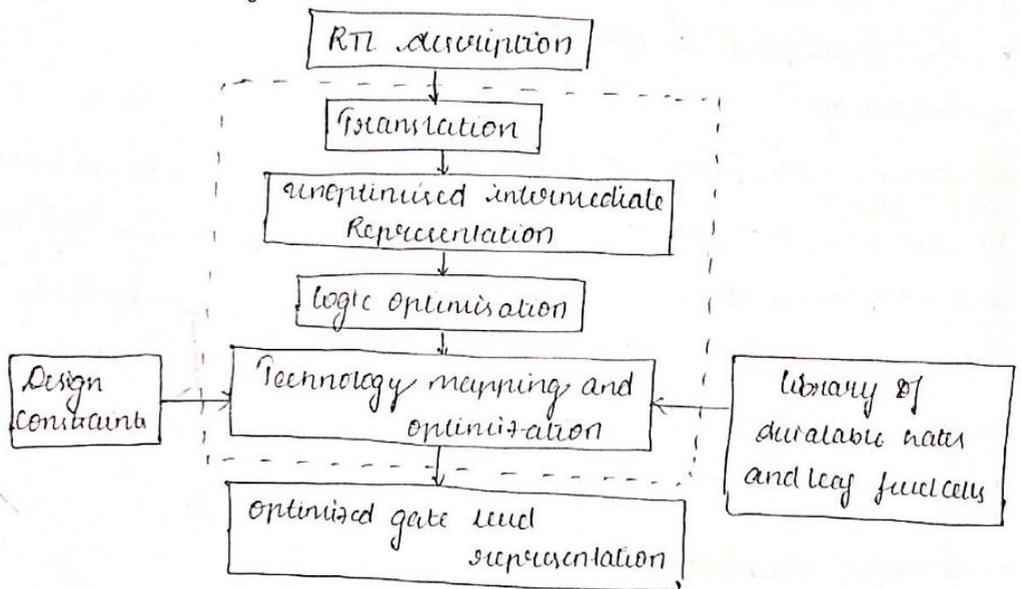
```
end module
```

Part B

17. write a short note on:

a) synthesis design flow:

The RTL synthesis flow follows several stages from RTL description to optimized gate level optimisation as shown.



i) RTL description

The designer describes the design at a high level by using RTL constructs of the HDL language. The designer spends time in functional verification to ensure that the RTL description functions correctly. After the verification of functionality, the RTL description is input to the hardware and computer logic synthesis tool.

ii) Translation

The RTL description is converted by the synthesis tool to an unoptimized intermediate, internal representation. This process is called translation.

The design constraints such as area, timing and power are not considered in the translation process.

iii) unoptimized intermediate Representation:

The design is represented internally by the synthesis tool in terms of internal data structures.

iv) Logic optimization:

Logic is now optimized to remove redundant logic. The techniques incorporate several algorithms and rules to convert an unoptimized Boolean description to optimized one. This process is called logic optimization.

Technology Mapping and optimization:

In this step, the synthesis tool takes the internal representation and implements the representation in gates, using the cells provided in the technology library, where by the design is mapped to the desired target technology such as CPLD, FPGA and ASIC chip technologies.

Technology library:

It contains library cells provided by the chip manufacturing company depending on technology used. The library cells are the basic building blocks that the chip manufacturing company uses for fabrication. The library cells can be basic logic gates (AND, OR, NOT, NAND, NOR, XOR, XNOR), multiplexers and special flip-flops.

Optimized gate level Description:

After the completion of technology mapping, an optimized gate level netlist described in terms of target technology

ponents is produced. If the netlist meets the required constraints, it is handed to the chip manufacturing company.

## IC Fabrication

The functional verification is done by identical stimulus that is run with the original RTL and synthesised gatelevel descriptions of the design. Then the output is compared to find any mismatches. If the output is not identical the designer needs to check any practical bugs and overrun the whole flow until all the bugs are eliminated.

## b) Sequential and Parallel blocks

### Sequential blocks

In sequential blocks we use begin and end keywords to group statements. Statements in a sequential block execute in sequence.

### Characteristics of sequential blocks

1) The statement in a sequential block are processed in the order they are specified.

2) A statement is executed only after execution of its preceding statement

3) If delay (or) event control is specified, it is relative to the stimulation time when the previous statement in the block completed execution.

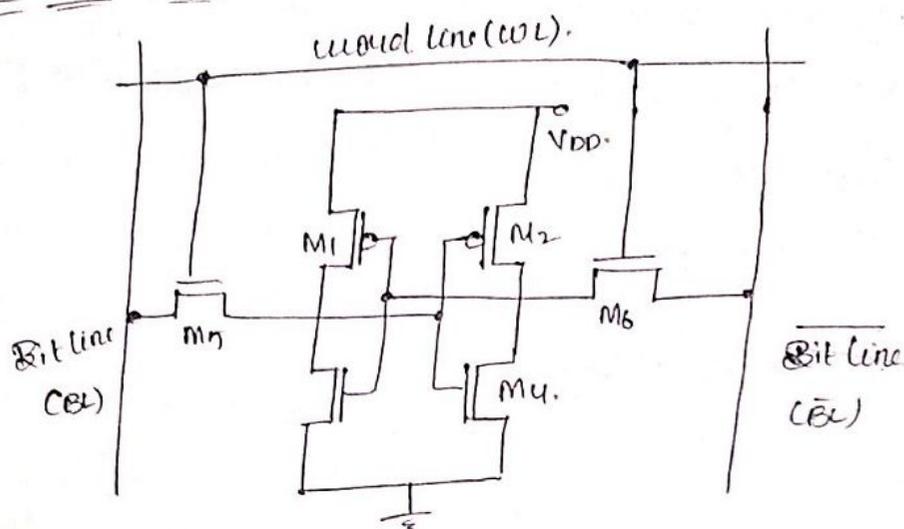
### Parallel Blocks

The keywords fork and join are used in parallel blocks. Statements in parallel blocks execute concurrently.

Ordering of statement is controlled by the delay (or) event control assigned to each statement.

If delay (or) event control is specified, it is relative to the entered time of the block. The order in which the statements are written in the block is not important.

### c) 6T SRAM cell:



A SRAM 1-bit memory cell with 6-transistors is shown above. The two CMOS inverters are connected back-to-back. Transistors  $M_1$  and  $M_3$  form one inverter, and transistors  $M_2$  and  $M_4$  form another inverter. The transistors  $M_5$  and  $M_6$  are used as switch controlled by word line.

Read operation: To read data from the cell, word line is enabled. This makes transistors  $M_5$  and  $M_6$  ON. Hence, the stored data is available in both the true and complemented form in the bit line and  $\overline{\text{bit line}}$ , respectively.

Write operation:

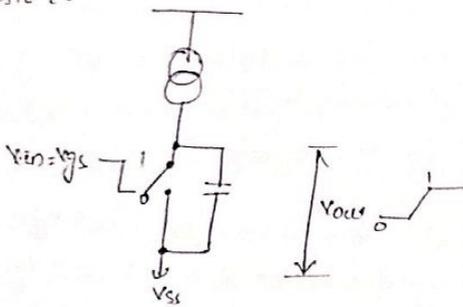
To write data into the cell, again word line is enabled. The data to be written is made available on the bit lines. The data is stored in the latch.

How to estimate the delay of CMOS inverter? Give the procedure to obtain delay.

The estimation of delay associated with the CMOS inverter is done by splitting the OP transitions into full time ( $t_f$ ) and rise time ( $t_r$ ) corresponding to charging and discharging of the capacitive load ( $C_L$ ). The charging and discharging are estimated independently to calculate the overall delay accurately.

### Rise-time estimation

The capacitive load is driven by the pull-up p-device and assume that it is to be in saturation and resistive region during for the entire charging period of the load capacitor ( $C_L$ ). charging of  $C_L$  is divided into saturation and resistive region of transistor.



The saturation current for p-transistors is given by,

$$I_{Dsp} = \frac{(V_{gs} - |V_{tp}|)^2 \beta_p}{2} \quad \text{--- (1)}$$

OP voltage when the above current is being constant is given by

$$V_{out} = \frac{I_{Dsp}}{C_L} \quad \text{--- (2)}$$

Sub. eq. (1) in (2)

$$t = \frac{2C_L V_{out}}{(V_{gs} - |V_{tp}|)^2 \beta_p}$$

If  $t = T_r$  when  $V_{out} = V_{DD}$ , then the corresponding  $T_r$  is given by

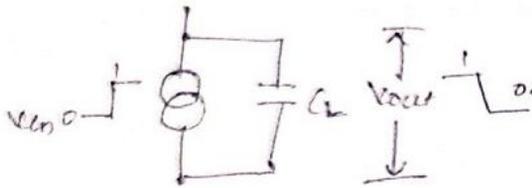
$$T_r = \frac{2C_L V_{DD}}{(V_{DD} - |V_{tp}|)^2 \beta_p}$$

But  $|V_{tp}| = 0.2V_{DD}$ , then  $T_r$  becomes.

$$T_r \approx \frac{3C_L}{V_{DD} \beta_p} \quad \text{--- (2)}$$

### Rise-time Estimation

Estimation of fall-time associated with the discharging of  $C_L$  through the pull-down n-type device.



By taking the similar process of rise-time, the fall-time becomes to

$$T_f \approx \frac{3C_L}{V_{DD} \beta_n}$$

from eq (1) and (2)

$$\frac{T_r}{T_f} \approx \frac{\beta_n}{\beta_p}$$

If  $\beta_n \approx 2.5\beta_p$  then  $\mu_n = 2.5\mu_p$ ; here  $\mu_n$  and  $\mu_p$  are different from each other. From this we can say that rise-time is slower by a factor of 2.5 when size of both the n and p-devices are minimum.

By putting channel length minimum, symmetrical operation can be achieved by  $w_p = 2.5w_n$ .

where,  $w_p$  = channel width of p-device  
 $w_n$  = channel width of n-device

As per the minimum size lambda-based design rules,

Input capacitance of inverter for p-device =  $2.5C_g$

Input capacitance of inverter for n-device =  $1C_g$

then, the total capacitance =  $2.5C_g + 1C_g = 3C_g$ .

Some analytical models are used to get the optimistic results for rise time and fall-time.

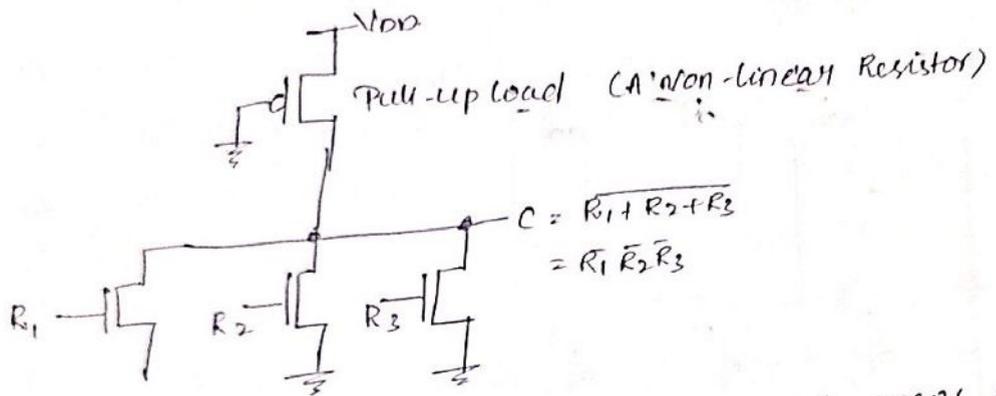
Factors affecting rise-time and fall-time are,

$T_r$  and  $T_f$  are proportional to  $C$ .

$T_r$  and  $T_f$  are proportional to  $\sqrt{V_{DD}}$

$T_r = 2.5 T_f$ , for n and p-transistor geometries.

16.b) Draw NOR based ROM memory. Explain its operation.



The PMOS pull-up transistor is replaced by a single PMOS with its gate tied up to  $V_{DD}$ , hence being permanently on acting as a load resistor. If none of the NMOS transistors are activated (all  $R_i$  being low), then the output signal  $C$  is high.

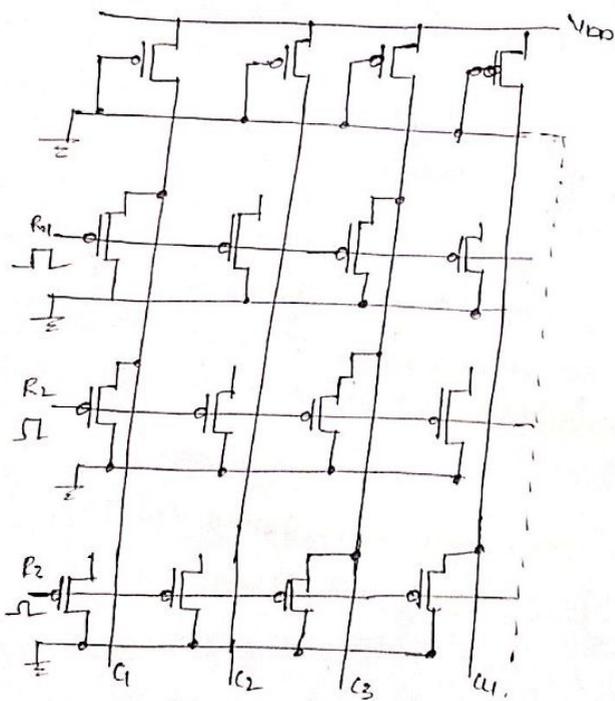
If any one of the NMOS transistor is activated ( $R_i$  being high) then the output signal  $C$  is low. To reduce the power consumption the gate of the PMOS pull-up transistor is connected to a clock signal. The power is consumed only during low period of the clock.

A NOR-based ROM consists of  $m$   $n$ -input pseudo-NMOS NOR gates, one  $n$ -input NOR per column, as shown.

Each memory cell is represented by one PMOS-NMOS transistor and binary information is stored by connected (or) not the drain terminal of such a transistor to the bit line. For every row

address only one word line is activated by applying a chip signal to the gates of nmos transistors in a row. If a selected transistor in the  $i^{\text{th}}$  column is connected to a bit line then the logic '0' is stored in this memory cell. If the transistor is not connected, then the logic '1' is stored.

15a) with the help of



	$C_1$	$C_2$	$C_3$	$C_4$
$R_1$	0	1	0	1
$R_2$	0	0	1	0
$R_3$	1	1	0	0

15a) with the help of circuit diagram, explain 4-bit barrel shifter.

A barrel shifter is a digital logic circuit that can shift a data word by a specified number of bits in one clock cycle. It can be implemented as a sequence of multiplexers and in such an implementation the output of one multiplexer is connected to the input of next multiplexer in a way

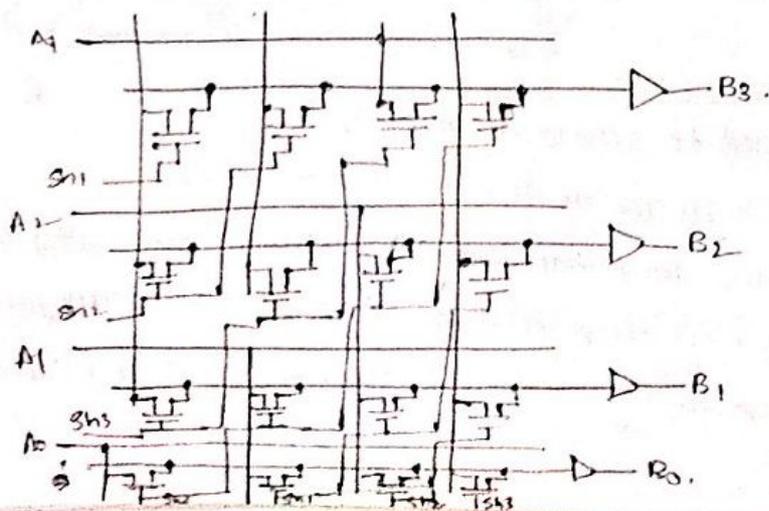
depends on the shift distance

The structure of barrel shifter is shown. It consists of an array of transistors, in which the number of rows equals the word length of the data and the number of columns equal the maximum shift width. In this case, both are set equal to four. The control wires are routed diagonally through the array.

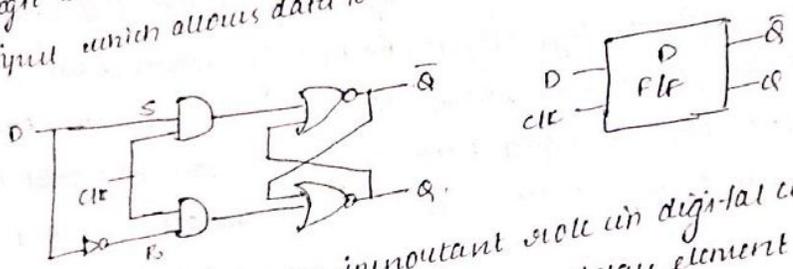
Barrel shifter needs a control wire for every shift bit. For example, a four bit shifter needs four control signals. To shift over three bits, the signal  $S_3$  should take on the value 1000. Only one of the signal is high. In a processor, the required shift value normally comes in an encoded binary format, which is substantially more compact. For instance, the encoded control word needs only two control signal and is represented as 11 for a shift over three bits. To translate the latter representation into the former, an extra module called a decoder is required.

A major advantage of this shifter is that a signal has to pass through at most one transmission gate. In other words, the propagation delay is theoretically constant and independent of the shift value or shifter size. This is not true in reality, however, because the capacitance at the input of the buffer ~~is~~ rises linearly with the maximum shift width.

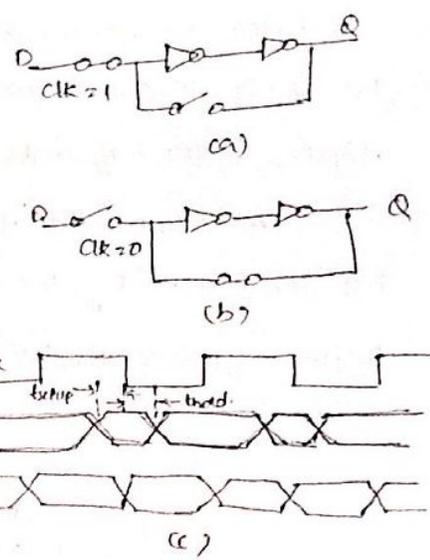
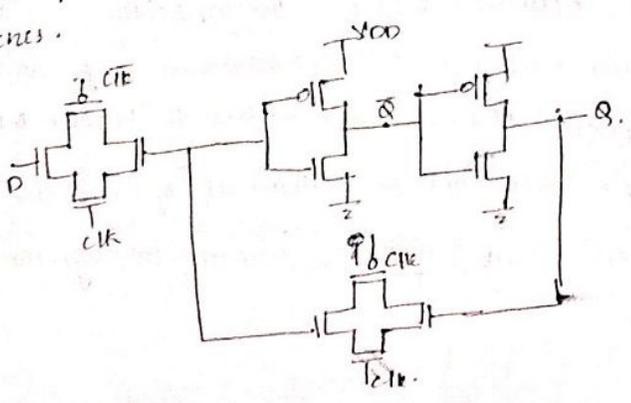
An important property of this circuit is that the layout size is not dominated by the active transistors, as in the case of all other arithmetic circuits, but by the number of wires running through the cells,



15. b) Design D flip-flop using transmission logic gate  
 In the digital integrated circuits, a large techniques for selection of  
 based sequential circuit have gained popular,  
 The gate level schematic of D flip-flop by modifying NOR based  
 SR latch. The input variable D is also inverted and connected to the S input  
 of flip-flop. It is clear from the schematic that when clock is active (high)  
 the output Q acquires the value of input D. When the clock is equal to  
 logic low, the output will preserve its state. Here, the clock is an enable  
 input which allows data to be accepted into the D flip-flop when active.



D flip-flop play many important role in digital circuits, primarily  
 for temporary storage of data (as a delay element) and we will  
 examine the simple CMOS implementation of D flip-flop as shown, which  
 consists of two inverters loop and two CMOS of transmission gate (TG)  
 switches.



clock signal is used to activated the TGs,  
 when clock is logic high then at the TG is activated,  
 whereas the TG in the another loop is activated when clock is low (ie) CLK is  
 logic high. Thus when clock is high input D is transferred into the  
 latch and when clock is logic low the previous state is preserved by the

stop. we can replace the  $\tau_n$  by a simple switch to better understand the operation of D-flipflop, for both pulses of clock where  $1r$  and  $0r$  signals should be valid.

It should be noted that the valid input  $D$  must be stable for a short time before (setup time  $t_s$ ) and after (hold time  $t_h$ ) the negative clock transition, during which the input switch opens and loop switch closes. Once the inner loop is completed by closing the loop switch, the output will preserve its valid level. For designing the D-latch, the requirements for setup time and hold time should be met. Any mistake for such specification can cause metastable problem which lead to unpredictable result.

14a) Draw and explain nmos fabrication process.

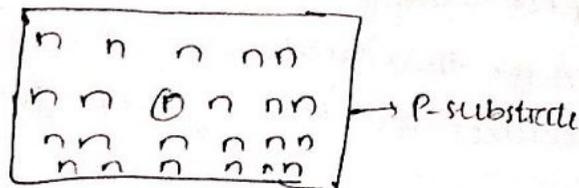
nmos fabrication

Step 1: Processing is carried out on a thin layer wafer cut from a single crystal of silicon of high purity into which the required p-impurities are introduced.

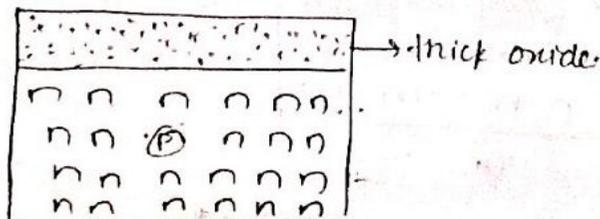
wafer dimensions (typically)

75 to 150mm — diameter  
0.4mm — thickness.

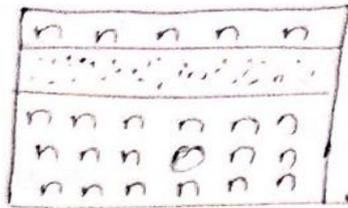
Doped with impurity concentrations of  $10^{15}/\text{cm}^3$  to  $10^{16}/\text{cm}^3$  given its resistivity as 25  $\Omega\text{cm}$  to 20  $\Omega\text{cm}$ .



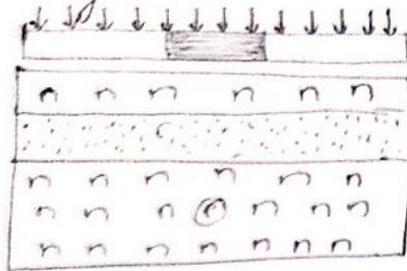
Step 2: A layer of  $\text{SiO}_2$ , typically 1  $\mu\text{m}$  thick is grown.



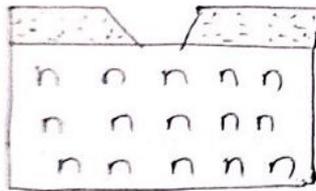
Step 1: surface is now covered with a photo resistor.



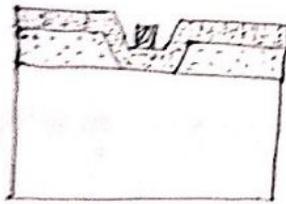
Step 2: surface photo resistive layer is then exposed to UV light through a mask which defines these regions into which diffusion is to take place together with transistor channel.



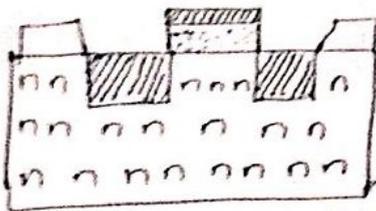
Step 3: these areas are subsequently readily etched away together with underlying  $SiO_2$ .



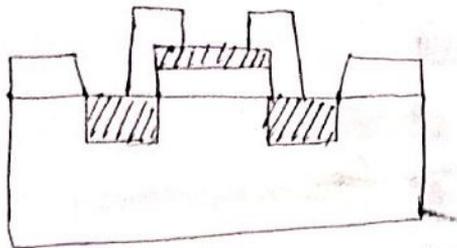
Step 4: the remaining photo resistor is removed & a thick layer of  $SiO_2$  [0.5  $\mu m$  typically] is grown over the chip surface & then polysilicon is deposited on top of this to form the gate structure.



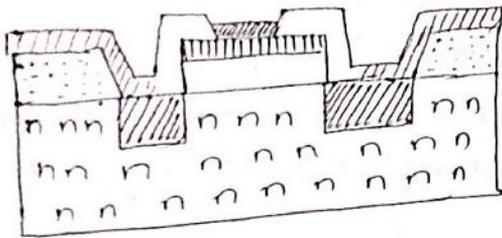
Step 5: thinner, photoresistive coating & masking allow the polysilicon to be patterned & then the thin oxide is removed to exposed areas into which n-type impurities are to be diffused from source to drain.



Step 8: Thick oxide is grown all over again & is then masked with photo-resist & etched to expose selected areas of the polysilicon gate & the drain & source areas where connections are to be made.



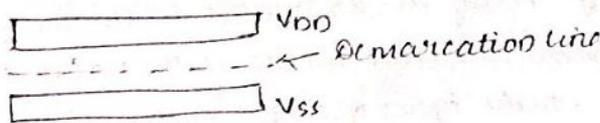
Step 9: The whole chip then has metal deposited over its surface to a thickness typically of  $1\mu\text{m}$ .



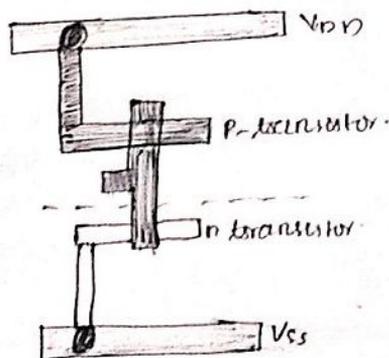
14b) What is the difference between stick diagram and layout diagram. Draw a stick diagram of a CMOS inverter.

CMOS inverter  $V = \bar{A}$

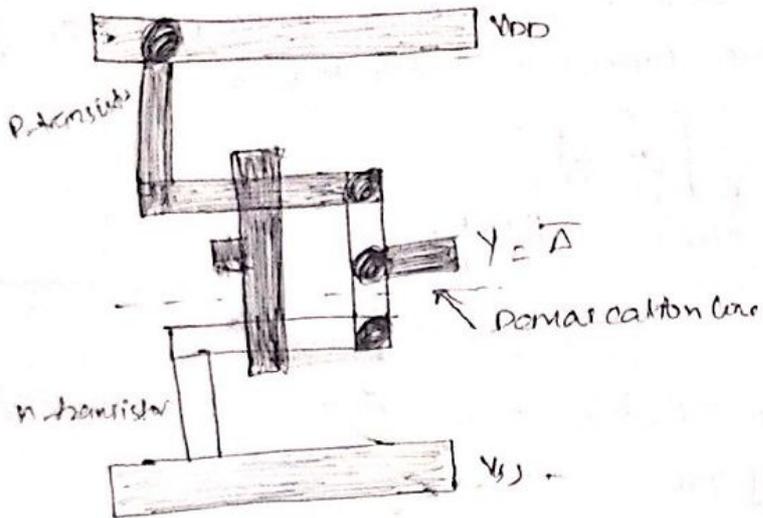
Step 1:



Step 2:

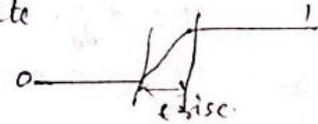


Steps:

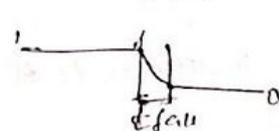


11. a) Explain gate delay with example. modeling was the facility to account for different types of propagation delay of circuit elements. any connection can cause a delay due to the distributed nature of its resistance & capacitance. there are 3 types of delays from ip to the op of primitive gate

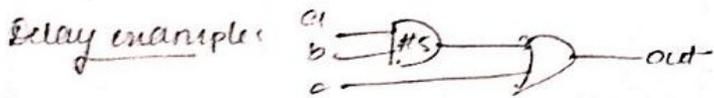
1) Rise delay: the rise delay is associated with gate output transition to 1 from another value.



2) Fall delay: the fall delay is associated with gate output transition to a '0' from another value.



3) Turn-off delay: the turn off delay is associated with the gate output transition to the high impedance value from another value. if the value changes to 1, the min of 2 delays is considered. these types of delay specification are allowed.



module delay (out, a, b, c);

input a, b, c;

output out;

use n;

# n and n1 (n, a, b)

# u or n2 (out, n, c);

end module;

11) b) write program for 16:1 mux using 4:1 mux in data flow model with test bench.

module mux16to1 (y, a, b, c, d, e, f, g, h, i, j, k, l, m, n, o, p, s0, s1, s2, s3)

b, c, d, e, f, g, h, i, j, k, l, m, n, o, p, q, r, s, t, u, v, w, x, y, z;

y;

q, r, s, t;

assign q = ((s0) \* (s1) \* a) | ((s0) \* s1 \* b) | ((s1) \* (s0) \* c) | (q) \* (s0) \* d;

assign r = ((s0) \* (s1) \* e) | ((s0) \* s1 \* f) | ((s1) \* (s0) \* g) | (s1) \* s0 \* h;

assign s = ((s0) \* (s1) \* i) | ((s0) \* s1 \* j) | ((s1) \* (s0) \* k) | s1 \* s0 \* d;

assign t = ((s0) \* (s1) \* m) | ((s0) \* s1 \* n) | ((s1) \* (s0) \* o) | (s1 \* s0 \* p);

assign y = ((s2) \* (s3) \* q) | ((s2) \* s3 \* r) | ((s3) \* (s2) \* s) | (s2 \* s3 \* t);

End module.

testbench

timescale 1ns/1ps

module mux16to1\_test;

sig a, b, c, d, e, f, g, h, i, j, k, l, m, n, o, p, s0, s1, s2, s3;

wire y;

mux16to1 uut (y, a, b, c, d, e, f, g, h, i, j, k, l, m, n, o, p, s0, s1, s2, s3);

initial begin

{s0, s1, s2, s3, a, b, c, d, e, f, g, h, i, j, k, l, m, n, o, p} = 0;

#5 {s0, s1, s2, s3, a, b, c, d, e, f, g, h, i, j, k, l, m, n, o, p} = 1;

#

#5 {s0, s1, s2, s3, a, b, c, d, e, f, g, h, i, j, k, l, m, n, o, p} = 16, 274

end

endmodule

Q2) Explain with help of example, diff b/w for and begin end.

beginend:-

In sequential block we use begin & end keywords to group statements. stmt is a sequential block executes in sequence.

Characteristics

The stmt in a sequential block are processed in the order they are specified. A stmt is executed only after execution of its preceding stmt.

Example

mainframe generation:

begin

#2 ve\_stream = 1;

#5 ve\_stream = 0;

#2 ve\_stream = 1;

#4 ve\_stream = 0;

#2 ve\_stream

#5

end.

fork-join:-

The keywords fork & join are used in parallel blocks. Statements in a parallel block execute concurrently.

Characteristics:-

Statements in a parallel block are executed concurrently.

Ordering of statements is controlled by the delay or event control assigned to each.

If delay or event control is specified it is relative to the entered of the block.

example:-

fork-join generation:-

fork:-

```
#12 reg-stream = 1;
#7 reg-stream = 0;
#10 reg-stream = 1;
#14 reg-stream = 0;
#16 reg-stream = 1;
#21 reg-stream = 0;
```

Join:-

12b) 8-bit parallel adder using task & function

using task:-

```
module adder (sum, a, b);
output [2:0] sum, co;
input [3:0] a, b;
reg co;
reg [3:0] sum;
task adder4
output [2:0];
output co;
input [3:0] x, y;
begin
s[0:2] = x + y;
end
end-task
always@ (a, b)
begin
adder4 (sum [2:0], co, a [2:0], b [2:0]);
end
end module
```

function:

```

module adder (sum, co, a, b);
    output [3:0] sum, co;
    input [3:0] a, b;
    reg [3:0] sum, a, b;
    function [4:0] adder4;
    input [3:0] x, y;
    begin
        adder4 = x + y;
    end
end function
always @ (a, b)
begin
    {co, sum[3:0]} = adder4(a[3:0], b[3:0]);
end
end module

```

(3) Different types of delay module with example.

Delays are used to control Regular Assignment delay.

This method is used to assign delay value in a continuous assignment statement. The delay value is specified after the keyword assign. Any change in the values of in1 & in2 will result in a delay of 10 time units before recomputation of the expression in1 & in2; & the result is assigned to out. If the value of in1 & in2 are changed before 10 time units then the result propagation to out, then the values of in1 & in2 out the time of recomputation are considered. This is called as inertial delay.

ex) assign #10 out = in1 & in2  
// Delay in a continuous assign.

2) Implicit continuous assignment delay.

The implicit continuous assignment delay is used to specify both delay & an assignment on the out.

ex.  
// Implicit continuous assignment delay  
out #10 = in1 & in2;  
// same as  
out = in1 & in2;  
assign #10 out = in1 & in2;

3) Net declaration delay:  
we can specify delay on a net when it is declared without putting a continuous assignment on the net. If we ~~also~~ specify delay on net out, then the value change applied to the net out is also delayed. Net declaration delay can also be used in gate level modelling.

ex. // Net delays  
wire #10 out;

assign out = in1 & in2;

// the above stmt has the same effect as the following

wire out;

assign #10 out = in1 & in2;

3b) up-down counter:

```
module updowncounter (R, clock, L, E, up_down, S);
```

```
    parameter n=5;
```

```
    input [n-1:0] R;
```

```
    input clock, L, E, up_down;
```

```
    output [n-1:0] Q;
```

```
    reg [n-1:0] Q;
```

```
    integer direction;
```

```
    always @ (posedge clock)
```

```
    begin
```

```
        if (up_down)
```

```
            direction = 1;
```

```
        else
```

```
            direction = -1;
```

```
        if (L)
```

```
            Q <= R;
```

```
        else if (E)
```

```
            Q <= Q + direction;
```

```
    end
```

```
end module
```